

3.3 V 100/133 MHz Differential 1:8 HCSL-Compatible Push-Pull Clock ZDB/Fanout Buffer for PCIe[®]

NB3W800L

Description

The NB3W800L is a low-power 8-output differential buffer that meets all the performance requirements of the DB800ZL specification. The NB3W800L is capable of distributing the reference clocks for Intel[®] QuickPath Interconnect (Intel QPI and UPI), PCIe Gen1/Gen2/Gen3/Gen4, SAS, SATA, and Intel Scalable Memory Interconnect (Intel SMI) applications. A fixed, internal feedback path maintains low drift for critical QPI applications.

Features

- 8 Differential Clock Output Pairs @ 0.7 V
- Low-power NMOS Push-pull HCSL Compatible Outputs
- Cycle–to–cycle Jitter <50 ps
- Output-to-output Skew <50 ps
- Input-to-output Delay Variation <100 ps
- PCIe Phase Jitter: Gen3 <1.0 ps, Gen4 <0.5 ps RMS
- QPI 9.6GT/s 12UI Phase Jitter <0.2 ps RMS
- Pseudo-External Fixed Feedback for Lowest Input-to-Output Delay
- Individual OE Control; Hardware Control of Each Output
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NB3W800L



Figure 1. Simplified Block Diagram



Figure 2. Pin Configuration

Table 8. PIN DESCRIPTIONS

Pin #	Pin Name	Туре	Description
1	PWRGD/PWRDN#	IN	3.3 V Input notifies device to sample latched inputs and start up on first high assertion, or exit Power Down Mode on subsequent assertions. Low enters Power Down Mode.
2	GNDA	GND	Ground for Input Receiver and PLL Core
3	VDDR	PWR	3.3 V power for differential input clock (receiver). This VDD should be treated as an analog power rail and filtered appropriately.
4	CLK_IN	IN	0.7 V Differential true input
5	CLK_IN#	IN	0.7 V Differential complementary Input
6	SDA	1/0	Data pin of SMBus circuitry

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Table 8. PIN DESCRIPTIONS

Pin #	Pin Name	Туре	Description		
17	DIF1#	OUT	0.7 V differential complementary clock output		
18	OE1#	IN	Active low input for enabling DIF pair 1. This pin has an internal pull down. 1 =disable outputs, 0 = enable outputs		
19	VDD	PWR	Power supply, nominal 3.3 V		
20	NC	N/A	No Connection.		
21	DIF2	OUT	0.7 V differential true clock output		
22	DIF2#	OUT	0.7 V differential complementary clock output		
23	OE2#	IN	Active low input for enabling DIF pair 2. This pin has an internal pull down. 1 = disable outputs, 0 = enable outputs		
24	OE3#	IN	Active low input for enabling DIF pair 3. This pin has an internal pull down. 1 = disable outputs, $0 =$ enable outputs		
25	DIF3	OUT	0.7 V differential true clock output		
26	DIF3#	OUT	0.7 V differential complementary clock output		
27	VDD	PWR	Power supply, nominal 3.3 V		
28	DIF4	OUT	0.7 V differential true clock output		
29	DIF4#	OUT	0.7 V differential complementary clock output		
30	OE4#	IN	Active low input for enabling DIF pair 4. This pin has an internal pull down. 1 = disable outputs, 0 = enable outputs		
31	OE5#	IN	Active low input for enabling DIF pair 5. This pin has an internal pull down. 1 =disable outputs, 0 = enable outputs		
32	DIF5	OUT	0.7 V differential true clock output		
33	DIF5#	OUT	0.7 V differential complementary clock output		
34	VDD	PWR	Power supply, nominal 3.3 V		
35	DIF6	OUT	0.7 V differential true clock output		
36	DIF6#	OUT	0.7 V differential complementary clock output		
37	OE6#	IN	Active low input for enabling DIF pair 6. This pin has an internal pull down. 1 = disable outputs, 0 = enable outputs		
38	VDD	PWR	Power supply, nominal 3.3 V		
39	DIF7	OUT	0.7 V differential true clock output		
40	DIF7#	OUT	0.7 V differential complementary clock output		
41	OE7#	IN	Active low input for enabling DIF pair 7. This pin has an internal pull down. 1 = disable outputs, 0 = enable outputs		
42	VDD	PWR	Power supply, nominal 3.3 V		
43	NC	N/A	No Connection.		
44	VDDA	PWR	3.3 V power for the PLL core.		
45	NC	N/A	No Connection.		
46	NC	N/A	No Connection.		
47	100M_133M#	IN	3.3 V Input to select operating frequency. See Functionality Table for Definition		
48	HBW_BYP_LBW#	IN	Trilevel input to select High BW, Bypass or Low BW mode. See PLL Operating Mode Table for Details.		
49	GND	PWR	EPAD, must be connected to Ground		

Table 9. ABSOLUTE MAXIMUM RATINGS

	Symbol	Parameter	Conditions	Min	Тур	Max	Units
`	VDD, VDDA	3.3 V Supply Voltage (Notes 1, 2)	VDD for core logic and PLL			4.6	V
	V _{IL}	Input Low Voltage (Note 1)		GND 0.5			V
	V _{IH}	Input High Voltage (Note 1)	Except for SMBus interface			V _{DD} + 0.5	V
	VIHSMB	Input High Voltage (Note 1)	SMBU59917554k 70073.7.500190746225	B5 p397666769	6 92 48 06 09	017303741.693764	17661 10fB

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Table 12. DIF 0.7 V AC TIMING CHARACTERISTICS (Non-Spread or -0.5% Spread Spectrum Mode)
$(V_{DD} = V_{DDA} = 3.3 \text{ V} \pm 5\%, T_A = 0^{\circ}\text{C} - 70^{\circ}\text{C})$, See Test Loads for Loading Conditions.

			CLK = 100 MH		
Symbol	Parameter		Min	Мах	Unit
Tstab (Note 32)	Clock Stabilization Time			1.8	ms
Laccuracy (Notes 15, 19, 27, 33)	Long A	Long Accuracy		100	ppm
Tabs (Notes 15, 16, 19)	Absolute	No Spread	9.94900 for 100 MHz	10.05100 for 100 MHz	ns
	Min/Max Host CLK		7.44925 for 133 MHz	7.55075 for 133 MHz	
	Period	0.5% Spread	9.49900 for 100 MHz	10.10126 for 100 MHz	
			7.44925 for 133 MHz	7.58845 for 133 MHz	
Slew_rate (Notes 13, 15, 19)	DIFF OUT	Slew_rate	1.0	4.0	V/ns
Δ Trise / Δ Tfall (Notes 15, 19, 29)	Rise and Fall	Time Variation		125	ps
Rise/Fall Matching (Notes 15, 19, 30, 31)				20	%
VHigh (Notes 15, 18, 21)	Voltage High ((typ 0.70 Volts)	660	850	mV
VLow (Notes 15, 18, 22)			•	•	_

Table 13. ELECTRICAL CHARACTERISTICS – Current Consumption (V_DD = V

Table 15. ELECTRICAL CHARACTERISTICS – PHASE JITTER PARAMETERS

 $(V_{DD} = V_{DDA} = 3.3 \text{ V} \pm 5\%, \text{ TA} = 0^{\circ}\text{C}$ 70°C), See Test Loads for Loading Conditions. (Note 35)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{jphPCleG1}		PCIe Gen 1 (Notes 48, 49)		13	86	ps (p p)
t _{jph} PCleG2		PCIe Gen 2 Lo Band 10 kHz < f < 1.5 MHz (Note 48)		0.25	3.0	ps (rms)
		PCIe Gen 2 High Band 1.5 MHz < f < Nyquist (50 MHz) (Note 48)		1.05	3.1	ps (rms)
tjphPCIeG3		PCIe Gen 3 (PLL BW of 2 4 MHz, CDR = 10 MHz) (Notes 48, 50)		0.21	1.0	ps (rms)
t _{jphPCleG4}	Phase Jitter, PLL Mode (Note 47)	PCIe Gen 4 (PLL BW of 2 4 MHz, CDR = 10 MHz) (Notes 48, 50)		0.21	0.5	ps (rms)
t _{jphUPI}		UPI (9.6 Gb/s, 10.4 Gb/s or 11.2 Gb/s, 100 MHz, 12 UI)		0.7	1.0	ps (rms)
^t jphQPI_SMI		QPI & SMI (100 MHz or 133 MHz, 4.8 Gb/s, 6.4 Gb/s 12 UI) (Note 51)		0.14	0.5	ps (rms)
		QPI & SMI (100 MHz, 8.0 Gb/s, 12 UI) (Note 51)		0.1	0.3	ps (rms)
		QPI & SMI (100 MHz, 9.6 Gb/s, 12 UI) (Note 51)		0.08	0.2	ps (rms)
t _{jphPCleG1}		PCIe Gen 1 (Notes 48, 49)			10	ps (p p)
t _{jph} PCleG2		PCIe Gen 2 Lo Band 10 kHz < f < 1.5 MHz (Notes 48, 52)			0.3	ps (rms)
		PCIe Gen 2 High Band 1.5 MHz < f < Nyquist (50 MHz) (Notes 48, 52)			0.6	ps (rms)
t _{jphPCleG3}	Additive Phase Jitter, Bypass mode (Note 47)	PCIe Gen 3 (PLL BW of 2 4 MHz, 2 5 MHz, CDR = 10 MHz) (Notes 48, 50, 52)			0.2	ps (rms)
t _{jphQPI_SMI}		QPI & SMI (100 MHz or 133 MHz, 4.8 Gb/s, 6.4 Gb/s 12 UI) (Notes 51, 52)			0.2	ps (rms)
		QPI & SMI (100 MHz, 8.0 Gb/s, 12 UI) (Notes 51, 52)			0.1	ps (rms)
		QPI & SMI (100 MHz, 9.6 Gb/s, 12 UI) (Notes 51, 52)			0.1	ps (rms)

47. Applies to all outputs.
48. See http://www.pcisig.com for complete specs
49. Sample size of at least 100K cycles. This figures extrapolates to 108ps pk pk @ 1M cycles for a BER of 1 12.
50. Subject to final ratification by PCI SIG.
51. Calculated from Intel supplied Clock Jitter Tool v 1.6.3
52. For RMS figures, additive jitter is calculated by solving the following equation: (Additive jitter)² = (total jitter)² - (input jitter)²

Table 16. CLOCK PERIODS – Differentia	I Outputs with Spread Spectrum Disabled
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			Measurement Window							
		1 Clock	1 μs	0.1 s	0.1 s	0.1 s	1 μs	1 Clock		
SSC OFF	Center Freq. MHz	–c2c Jitter Abs Per Min	–SSC Short–Term Average Min	– ppm Long–Term Average Min	0 ppm Period Nominal	+ ppm Long–Term Average Max	+SSC Short–Term Average Max	+c2c Jitter Abs Per Max	Units	

DIF

MEASUREMENT POINTS FOR DIFFERENTIAL

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SIGNAL AND FEATURE OPERATION

CLK_IN, CLK_IN#

The differential input clock is expected to be sourced from a clock synthesizer with an HCSL–compatible output, e.g. CK420BQ, CK–NET, CK–uS, or CK509B or another driver.

OE# and Output Enables (Control Registers)

Each output can be individually enabled or disabled by SMBus control register bits. Additionally, each output of the DIF[7:0] has a dedicated OE# pin. The OE# pins are asynchronous asserted–low signals. The Output Enable bits in the SMBus registers are active high and are set to enable by default.

The disabled state for the NB3W800L low power NMOS Push–Pull outputs is Low/Low.

Please note that the logic level for assertion or deassertion is different in software than it is on hardware. Output is enabled if OE# pin is pulled low and still maintains software programming logic with output enabled if OE register is true.

The assertion and de–assertion of this signal is absolutely asynchronous.

OE# Assertion (Transition from '1' to '0')

All differential outputs that were tristated will resume normal operation in a glitch free manner.

OE# De-Assertion (Transition from '0' to '1')

Corresponding output will transition from normal operation to tri-state in a glitch free manner.

100M_133M# – Frequency Selection

The 100M_133M# is a hardware pin, which programs the appropriate output frequency of the DIF pairs. Note that the CLK_IN frequency is equal to CLK_OUT frequency. An external pull–up or pull–down resistor is attached to this pin to select the input/output frequency.

PWRGD/PWRDN#

PWRGD/PWRDN# is a dual function pin. PWRGD is asserted high and de-asserted low. De-assertion of PWRGD (pulling the signal low) is equivalent to indicating a powerdown condition. PWRGD (assertion) is used by the NB3W800L to sample initial configurations such as frequency select condition and SA selections.

After PWRGD has been asserted high for the first time, the pin becomes a PWRDN# (Power Down) pin that can be used to shut off all clocks cleanly and instruct the device to invoke power savings mode. PWRDN# is a completely asynchronous active low input. When entering power savings mode, PWRDN# should be asserted low **prior to shutting off the input clock or power** to ensure all clocks shut down in a glitch free manner. When PWRDN# is asserted low by two consecutive rising edges of DIF#, all differential outputs are held tri–stated on the next DIF# high to low transition. The assertion and de-assertion of PWRDN# is absolutely asynchronous.

WARNING: Disabling of the CLK_IN input clock prior to assertion of PWRDN# is an undefined mode and not recommended. Operation in this mode may result in glitches, excessive frequency shifting, etc.

Table 18. PWRGD/PWRDN# FUNCTIONALITY

PWRGD/PWRDN#	DIF	DIF#		
0	Tri state	Tri state		
1	Running	Running		

HBW_BYPASS_LBW#

The HBW_BYPASS_LBW# is a tri level function input pin. It is used to select between PLL high bandwidth, bypass mode and PLL low bandwidth mode.



POWER FILTERING EXAMPLE

Figure 7. Schematic Example of the NB3W800L Power Filtering

Buffer Power–Up State Machine

Table 19. BUFFER POWER-UP STATE MACHINE

State	Description
0	3.3 V Buffer power off
1	After 3.3 V supply is detected to rise above 3.135 V, the buffer enters State 1 and initiates a 0.1 ms-0.3 ms delay.
2	Buffer waits for a valid clock on the CLK input and PWRDN# de assertion (or PWRGD assertion low to high)
3	Once the PLL is locked to the CLK_IN input clock, the buffer enters state 3 and enables outputs for normal operation. (Notes 57, 58)

57. The total power up latency from power on to all outputs active must be less than 1.8 ms (assuming a valid clock is present on CLK_IN input). 58. If power is valid and powerdown is de asserted (PWRGD asserted) but no input clocks are present on the CLK_IN input, DIF clocks must

remain disabled. Only after valid input clocks are detected, valid power, PWRDN# de asserted (PWRGD asserted) with the PLL locked/stable and the DIF outputs enabled.



Device Power–Up Sequence

Follow the power–up sequence below for proper device functionality:

- 1. PWRGD/PWRDN# pin must be Low.
- 2. Assign remaining control pins to their required state (100M_133M#, HBW_BYPASS_LBW#, SDA, SCL)
- 3. Apply power to the device.
- Once the VDD pin has reached a valid VDDmin level (3.3V –5%), the PWRGD/PWRDN# pin must be asserted High. See Figure 9.

Note: If no clock is present on the CLK_IN/CLK_IN# pins when device is powered up, there will be no clock on DIF/DIF# outputs.



PWRGD

Figure 9. PWRGD and VDD Relationship Diagram

Byte 0	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	48	PLL Mode 1	PLL Operating Mode Rd back 1	R	See PLL Op Readba	erating Mode ck Table	

Table 24. SMBus TABLE: RESERVED REGISTER

Byte 4	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7			Reserved				0
Bit 6			Reserved				0
Bit 5			Reserved				0
Bit 4			Reserved				0
Bit 3			Reserved				0
Bit 2			Reserved				0
Bit 1			Reserved				0
Bit 0			Reserved				0

Table 25. SMBus TABLE: VENDOR & REVISION ID REGISTER

Byte 5	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7							

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BOTTOM VIEW



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